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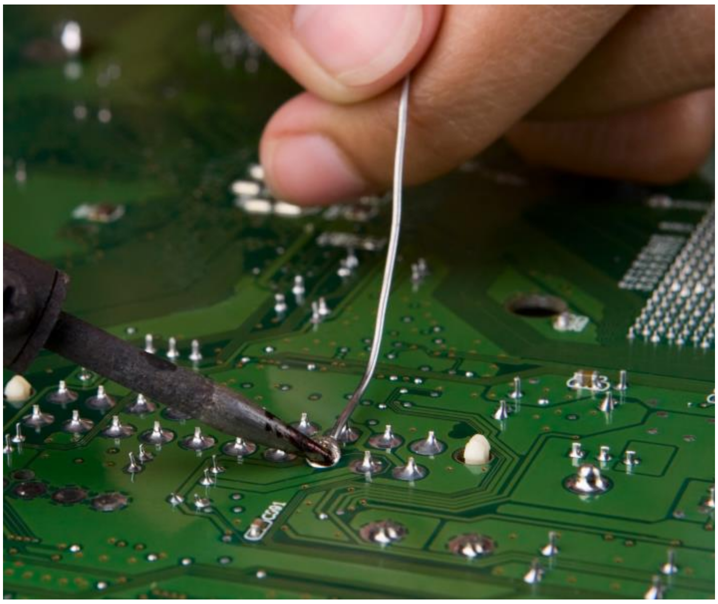
Lead Free Solder Products

EMC and Thermal Management Solutions



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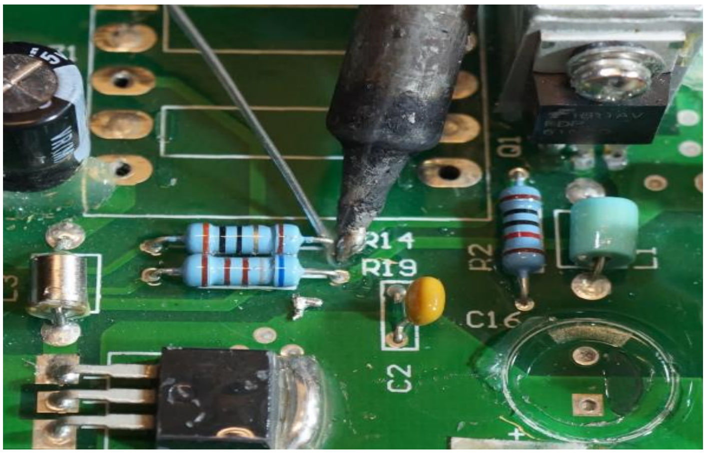
LEAD FREE SOLDER PRODUCTS



Fothershield distribute MG Chemicals superior Lead-Free flux cored solder wires, pastes and flux. The solders are made from virgin metals, have higher melting temperatures and wet metal surfaces more slowly. Joints will look different as the surfaces are not as reflective as tin-lead joints.

The lead-free wires maintain consistent solder and flux percentages. The typical flux percentages for lead-free solder is 2% to 4%, meet or exceed J-STD-004B and J-STD-006C, and are RoHS compliant.

FS-4900-227G 0.81mm Lead Free Solder Wire SN96

This electronics grade solder wire achieves a constant solder and flux percentage through a state-of-the-art extrusion wire drawing machine which constantly monitors the wire to prevent voids, and provides a consistant top grade solder wire. Typical flux percentages for our lead free solder is 2.0% to 4.0%.

FS-4900-227G is a complemented with a no-clean synthetically refined, splatter-proof resin flux core specifically used for high temperature lead free alloys which promotes fast wetting action and maximum wetting spread like an RA type. It is mild enough not to require cleaning and leaves a small amount of post-soldering residue that is non-conductive and non-corrosive. It will not cause electrical shorts. No clean refers to the fact that the flux residues are not harmful to assemblies, it does not mean there will be no residue, but any residues do not need to be removed in typical applications. Use this solder anywhere you would use a normal solder. Activator conforms to J-STD-004, RELO.

- Lead free
- RoHS compliant
- No clean flux
- Excellent wettability
- Hard non-conductive residues
- Melting point 217°C to 221°C
- Conforms to impurity requirements of J-STD-006
- 1 lb oflead free solder has 27% more length than leaded solder
- 96.3% tin, 0.7% copper, 3% silver

Part No.	Size	Diameter	Gauge	Flux %	Packaging
FS-4900-227G	227g	0.8mm	21	2.2	Spool
FS-4900-35G	35g	0.8mm	21	2.2	Tube

FS-4901-227G 0.81mm Lead Free Solder Wire SN99

FS-4901-227G lead free solder is an electronic grade solder wire which used high purity eutectic Sn 99.3/Cu 0.7 alloy complemented with a no clean synthetically refined, splatter proof resin flux core. Wetting and spreading like an RA type flux, it is virtually non-splattering and meets with J-STD-004 and exceeds J-STD-006 specifications. Suitable for use in food processing areas. Use this solder anywhere you would use a normal solder.

This wire is an economical substitute for the SAC305 solders. It leaves a small amount of post-soldering residue that is non-conductive and non-corrosive. The No Clean name refers to the fact that the flux residues are not harmful to assemblies and does not mean there will be no residue, but any residues do not need to be removed in typical applications.

- Lead free
- RoHS Compliant
- Halide free
- Silver free
- Eutectic alloy
- Resin spreads like rosin activated flux
- Excellent wettability
- Non splattering
- Non corrosive
- Non conductive
- NFS International Registered (No. 144209) as acceptable non-food compound for use on electrical equipment in and around food processing areas
- Melting point 227°C
- 99.3% tin, 0.7% copper

Part No.	Size	Diameter	Gauge	Flux %	Packaging
FS-4901-227G	227g	0.8mm	21	2.2	Spool

FS-4902P LEAD FREE LOW TEMPERATURE SOLDER PASTE

Made for low temperature applications the FS-4902P spreads and adheres well to a variety of materials giving excellent soldering results. Dispensing evenly and resisting solder beading and bright spots, the solder provides an excellent appearance. The paste provides high fluxing activity levels, promotes thermal stability and prevents thermal degradation when reflowing under normal atmospheric conditions, and exhibits superior joint strength and excellent wettability. The paste is designed for LED’s, telecommunication assemblies and radiators, printed circuit board assembly and repair.

- Long operational life – non slumping
- Excellent fine pitch printing capability
- Good wettability
- RoHS compliant
- Alloy exceeds J-STD-006C and meets ASTM B 32 purity requirements
- Flux meets J-STD-004B
- Melting point 138°C

Part No.	Size	Packaging
FS-4902P-15G	15g	Syringe
FS-4902P-25G	25g	Syringe

FS-4910-28G LEAD FREE SOLDER TIN TIP TINNER

Tip tinner ia a mixture of solder powder and thermally stable oxide-reducing compounds and is used to repairs oxidized soldering tips to extend the life and performance of new soldering tips.

Using the soldering iron at operating temperatures, roll or wipe the soldering iron tip over the surface of the Tip Tinner for a few seconds until the soldering tip is evenly tinned. Any remaining residues can be readily removed by wiping with a wet sponge.

- Used to clean and re-tip, and repair oxidised iron tips
- Easy to use
- Prolongs the life of new iron tips
- RoHS compliant
- 96.5% tin, 3.0% silver, 0.5% copper

Part No.	Size	Packaging
FS-4910-28G	28g	Tin